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Pixus Announces New Cooling Solutions for OpenVPX and MicroTCA Systems

Waterloo, Ontario — Apr 13, 2017 – Pixus Technologies, a provider of embedded computing and enclosure solutions, has introduced new RiCool V fans for enhanced intelligent cooling in several backplane-based computing solutions.

The Pixus reverse-impeller blowers require only 1U of space above the card cage to provide high-performance cooling. This approach helps keep the chassis height low, while providing more efficient and effective cooling than axial muffin fans that are often employed in the rear of an enclosure. Located directly above the card cage, the 12V RiCool V fans provide up to 200 Cubic Feet per Minute (CFM) of cooling and 3.2" of H2O static pressure.

The new fans from Pixus provide full shelf management functionality and are individually hot swappable. There is also a self-controlled (thermistor) version for non-intelligent applications. Pixus will utilize these blowers in front-to-rear cooled MicroTCA systems and in 3U/6U backplane systems (OpenVPX, CompactPCI Serial, VME64x) that require high airflow and reliability.

Pixus offers chassis platforms in OpenVPX, MicroTCA, AdvancedTCA, VME64x, and Compact formats. The company also offers instrumentation cases and components for embedded systems.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.